

GBJ6005 THRU GBJ610

GLASS PASSIVATED BRIDGE RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 6.0 Ampere

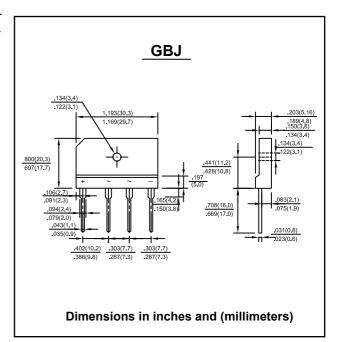
FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capabiliy

MECHANICAL DATA

- Case:Molded plastic, GBJ
- Terminals: Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any





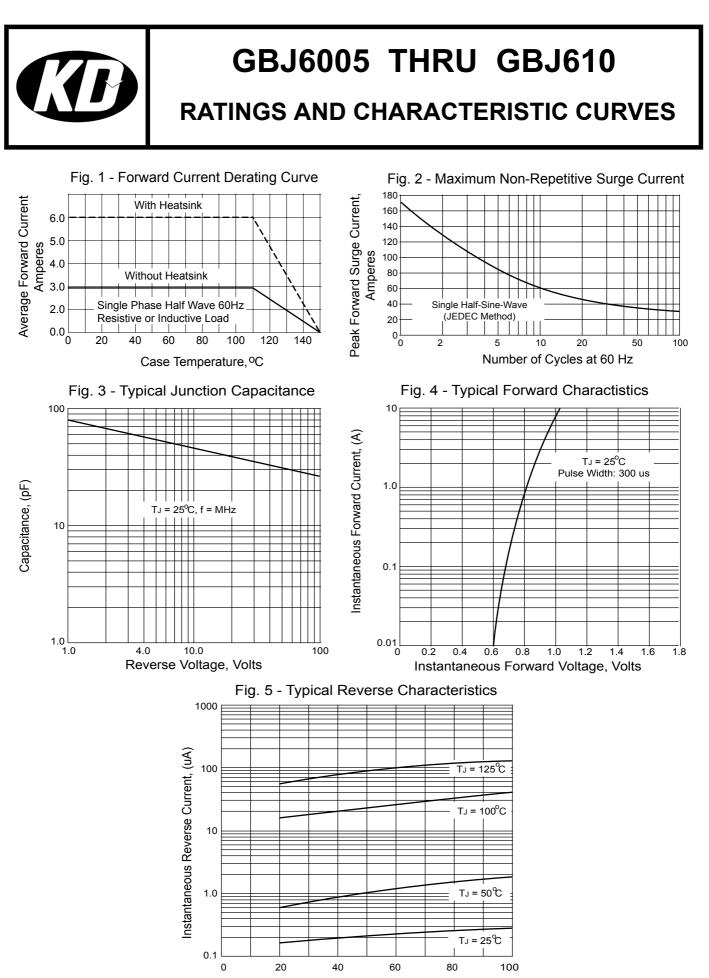
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	GBJ 6005	GBJ 601	GBJ 602	GBJ 604	GBJ 606	GBJ 608	GBJ 610	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current with Heatsink at T_{C} = 100 °C	I _(AV)	6							А
Peak Forward Surge Current, 8.3 ms Single Half-Sine -Wave superimposed on rated load (JEDEC Method)	I _{FSM}	170							А
Maximum Forward Voltage at 3.0 A DC and 25 $^{\circ}$ C	V _F	1.1							V
Maximum Reverse Current at $T_A = 25^{\circ}C$ at Rated DC Blocking Voltage $T_A = 125^{\circ}C$	I _R	5.0 500							μA
Typical Junction Capacitance ¹⁾	CJ	55							pF
Typical Thermal Resistance ²⁾	R _{θJC}	1.8							°C/W
Operating and Storage Temperature Range	T _J ,T _S	-55 to +150							°C

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

²⁾ Thermal resistance from junction to case with device mounted on 300 mm X 300 mm X 1.6 mm Cu plate heatsink.



Percent of Rate Peak Reverse Voltage, %